

Product Brief

SmartPIM and SmartPACK

Self-acting PressFIT assembly

We have added a new housing concept to our PressFIT technology – SmartPIM and SmartPACK.

Power electronics users are increasingly demanding easy-to-use connections and mounting technologies. The well-known PressFIT technology offers the possibility of solderless mounting combined with improved reliability in comparison to soldering.

We developed a completely new module family to meet evolving assembly and reliability demands. The sophisticated and reliable mounting concept combines the existing PressFIT contact with a very basic inverter mounting and assembly technology.

The brand-new housing allows the module to be connected to the heat sink and the PCB in a single-step mounting process. In the Smart1, this easy mounting concept is realized by using only one screw. During this mounting process, the PressFIT pin is pressed into the PCB, the PCB is stabilized and the module is mounted in the same step on the surface of the heat sink. The whole mounting concept needs no additional tools; only an electrical screw driver is used. All well-known electrical circuits are feasible. The housing supports currents of up to 75 A.



Key features

- > Safe and simple mounting process
- > Reduced assembly time
- > Reliable connection of module pins and PCB
- > Flexible mounting possibilities

Applications

- > Industrial drives
- > UPS/power supplies
- > Solar inverters
- > Aircon
- > Welding
- > Inductive heating



SmartPIM and SmartPACK

Building on the reliability of the established PressFIT technology, this new module family offers the following advanced features:

- > Press-in process by tightening the module
- > Flexible mounting possibilities
- > The new module and mounting concept reduce process time
- > Robust housing concept with decoupled DCB force
- > Gas-tight contact to avoid adverse effects from climate conditions
- > Decreased FIT rates for interconnections
- > Reliable cold-welded connection of module pins and PCB
- > Mounting possible on both sides of standard PCBs



Smart1 portfolio

I_c [A]	1200 V PIM	650 V PIM	1200 V sixpack	650 V sixpack
75				FS75R07U1E4
50		FP50R07U1E4	FSS0R12U1T4	FS50R07U1E4
35	FP35R12U1T4		FS35R12U1T4	
30		FP30R07U1E4		
25	FP25R12U1T4			
15				

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